



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

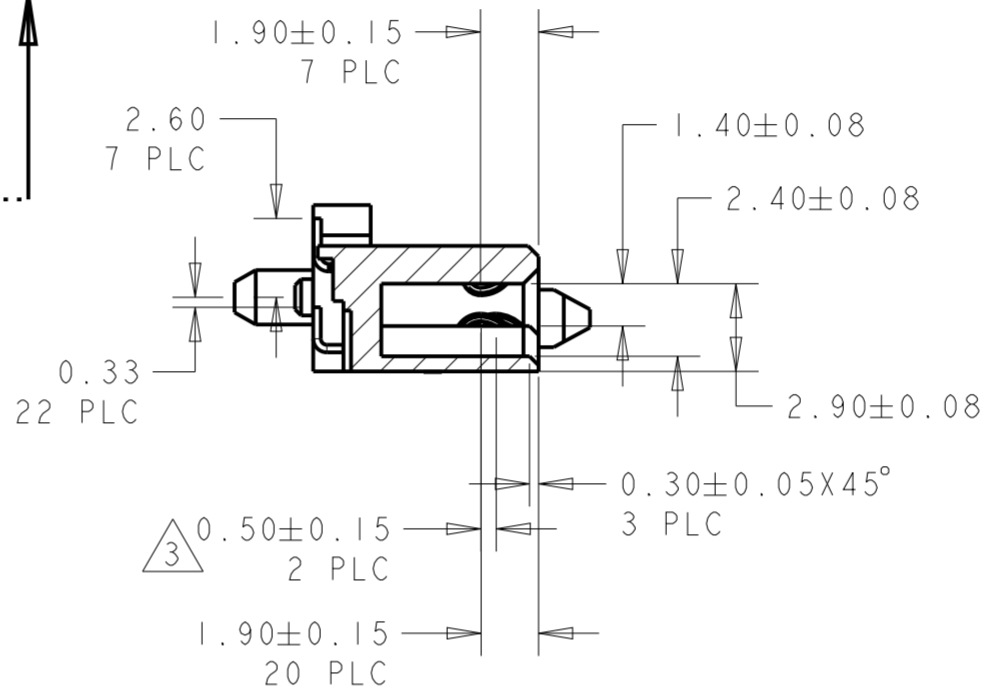
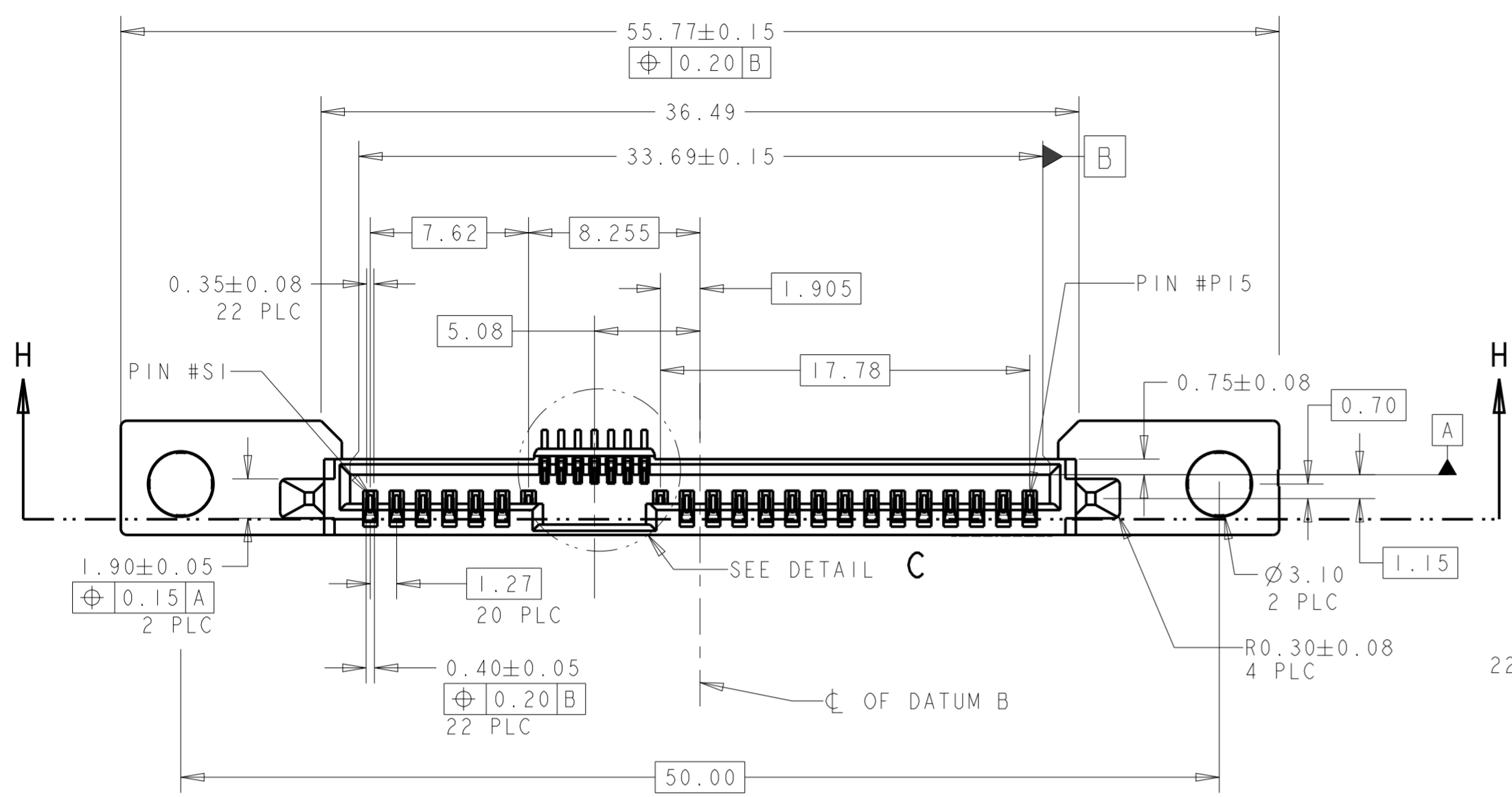
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

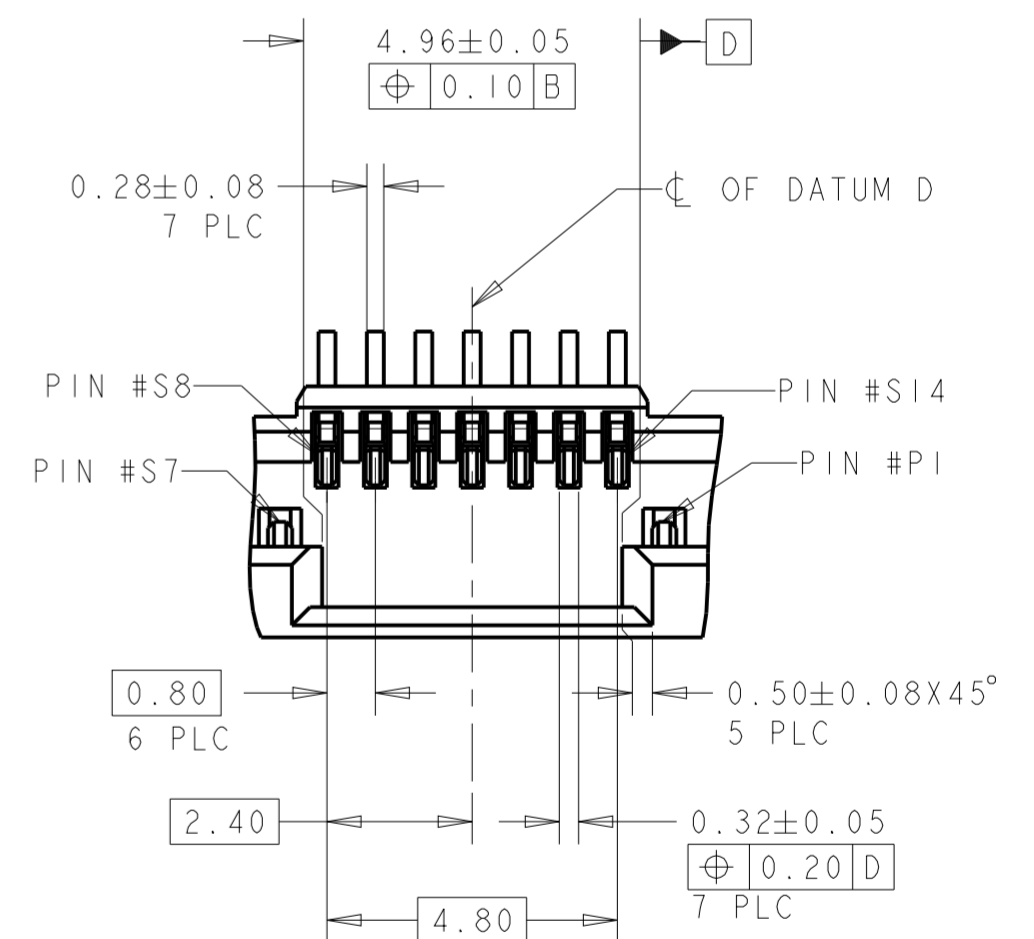
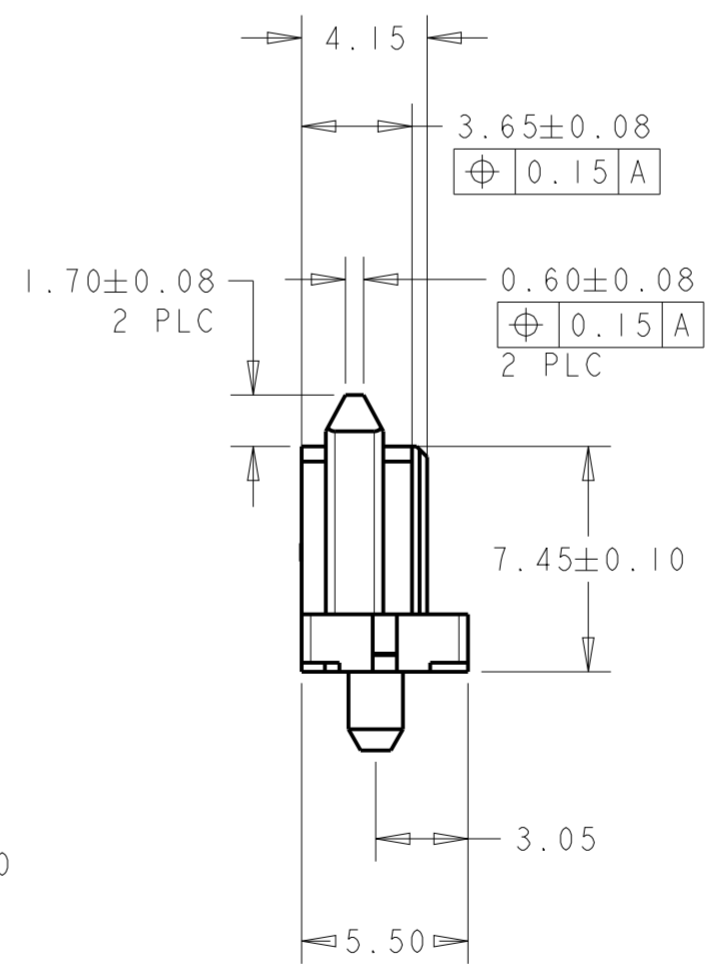
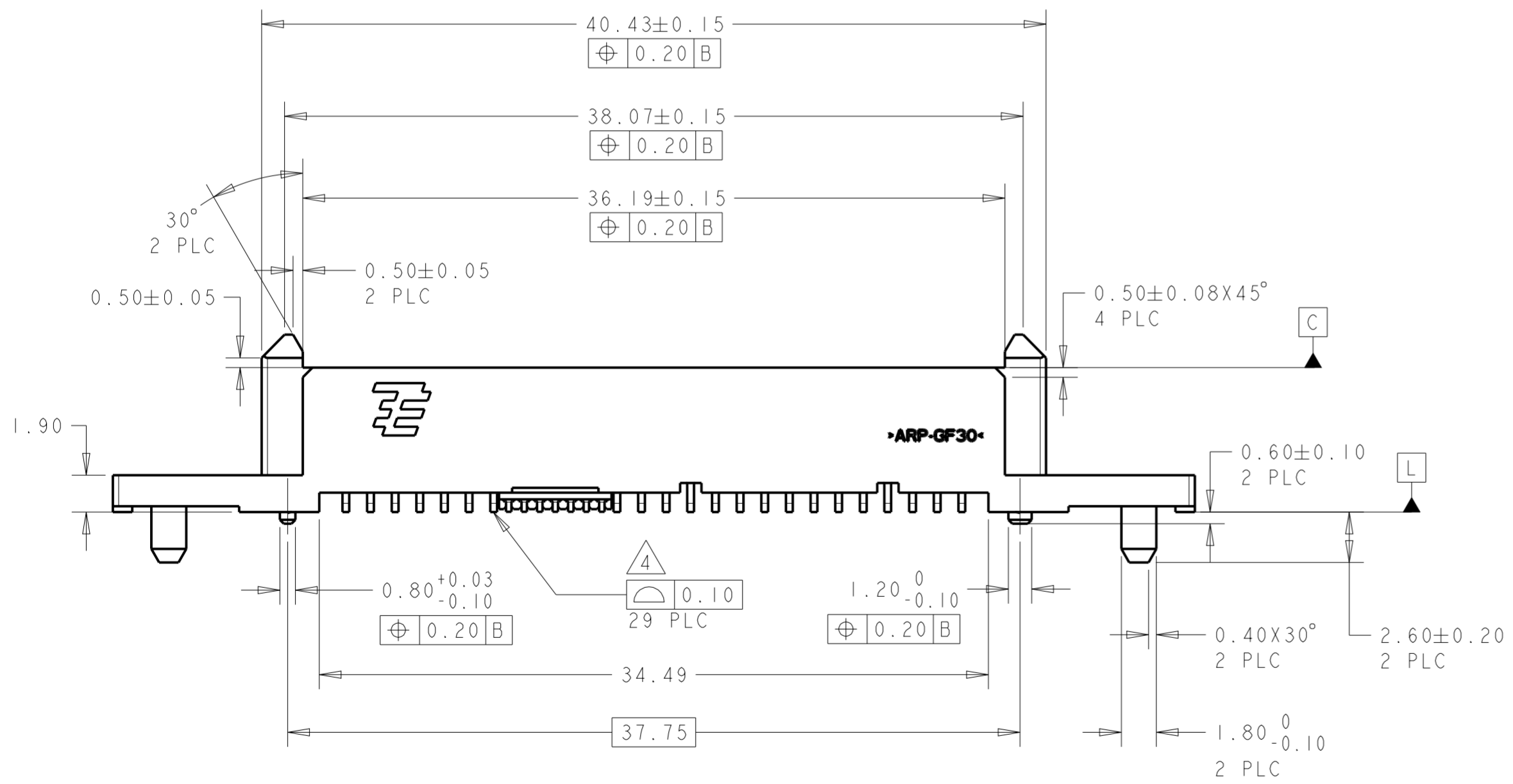


THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION .19  
 (C) COPYRIGHT 19 BY AMP INCORPORATED. ALL RIGHTS RESERVED.

LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
DY	-				
A		NPR PER ECR-11-005372	15MAR11	PTY	LSF
B		REVISED PER ECR-15-000604	15JAN2015	HW	JY



- NOTES:
- MATERIAL:  
HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0,  
COLOR: BLACK  
CONTACT: COPPER ALLOY  
ROUND POST: BRASS
  - FINISH:  
CONTACT AREA: MIN 0.76um GOLD PLATING  
SOLDERTAIL: MIN 2.54um MATTE TIN PLATING  
UNDERPLATE: MIN 1.27um NICKEL PLATING  
ROUND POST PLATING: MIN 2.54um TIN OVER  
MIN 1.27um NICKEL UNDERPLATE
  - PIN #P4 AND #P12 ONLY. PREMATING PINS
  - SOLDERTAIL TO BE 0.05 MAX ABOVE AND  
0.10 MAX BELOW DATUM E
  - 1.33 MAX MEASURED AT DATUM C
  - ROUND POSTS ARE SOLDERABLE
  - ELECTRICAL SPECIFICATION:  
MAXIMUM RATED CURRENT: 1.5Amps @ 30°C MAX  
CONTACT RESISTANCE: 30 MILLI-OHMS MAX  
INSULATOR RESISTANCE: 1000 MEGOHMS MIN  
DIELECTRIC WITHSTANDING VOLTAGE: 500 V AC



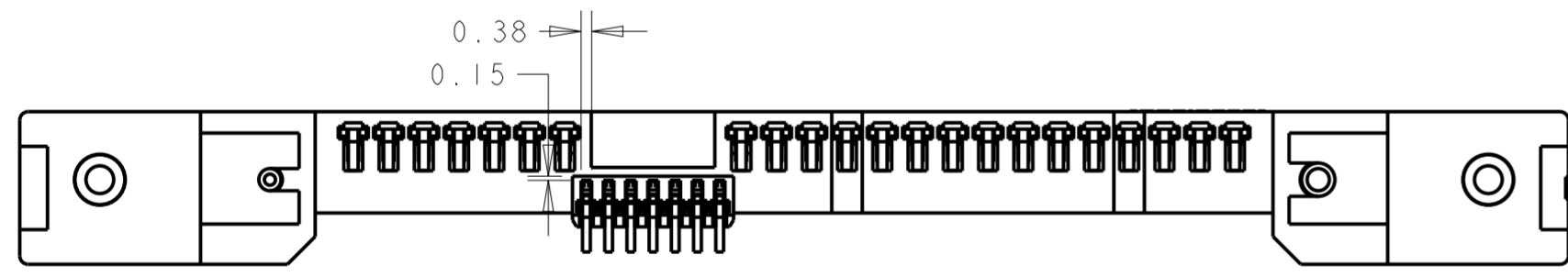
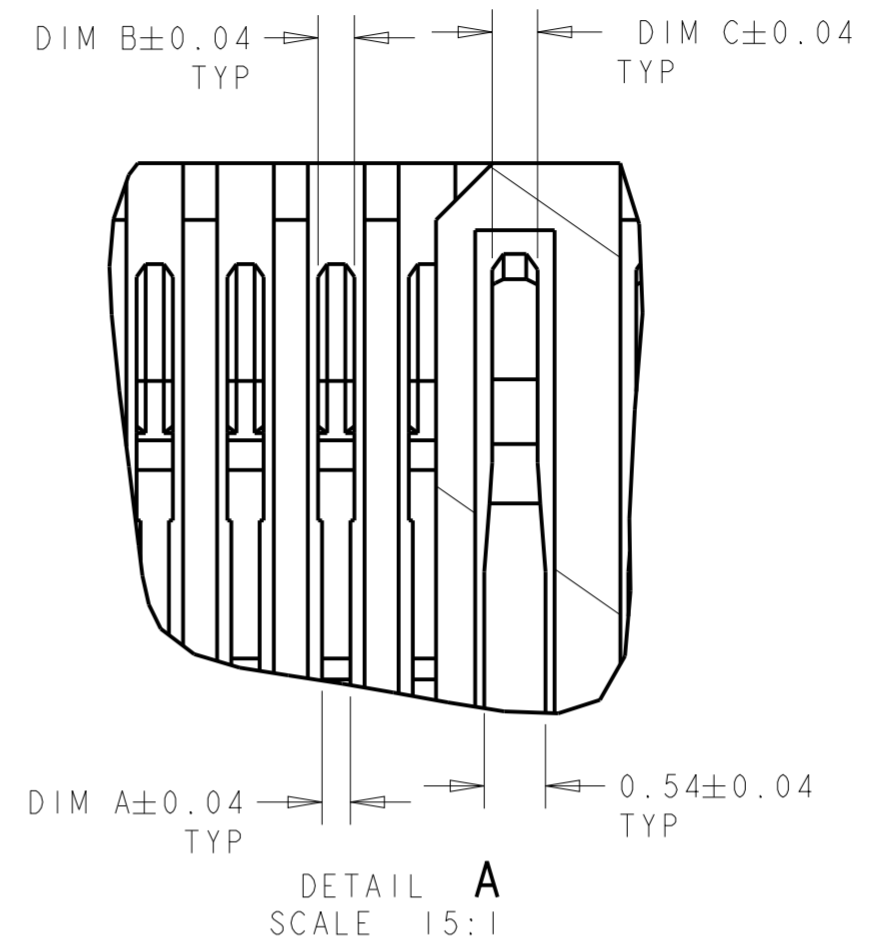
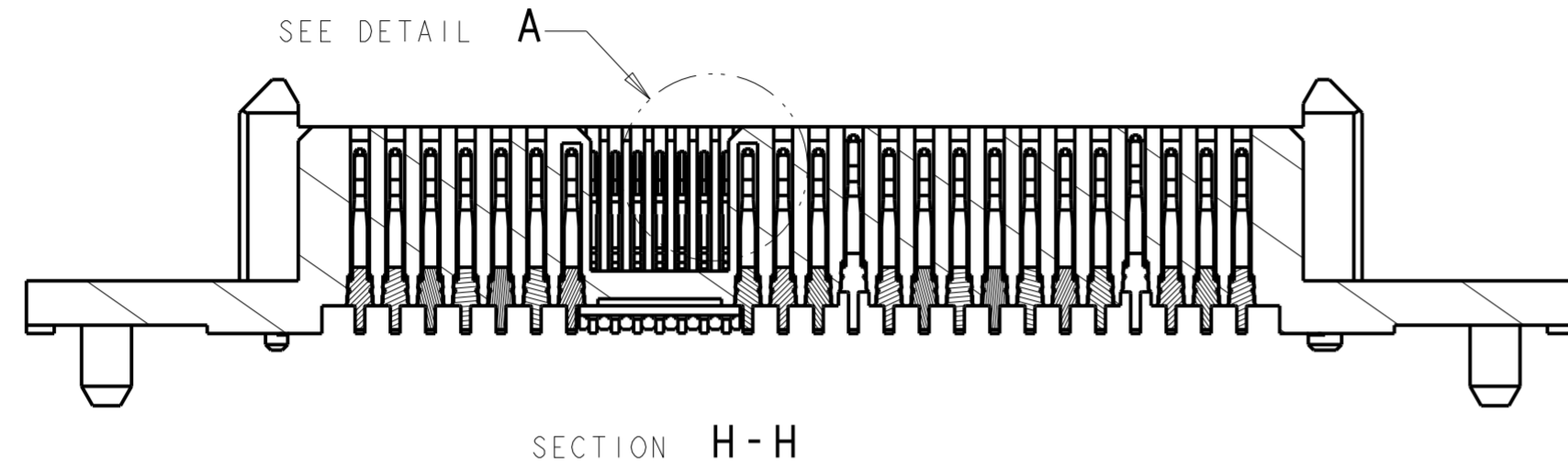
DETAIL C  
SCALE 8:1  
P/N: 1735871-1 AS SHOWN

0.54	0.34	0.34	1735871-3
0.54	0.39	0.34	1735871-2
0.40	0.32	0.25	1735871-1
DIM C	DIM B	DIM A	P/N

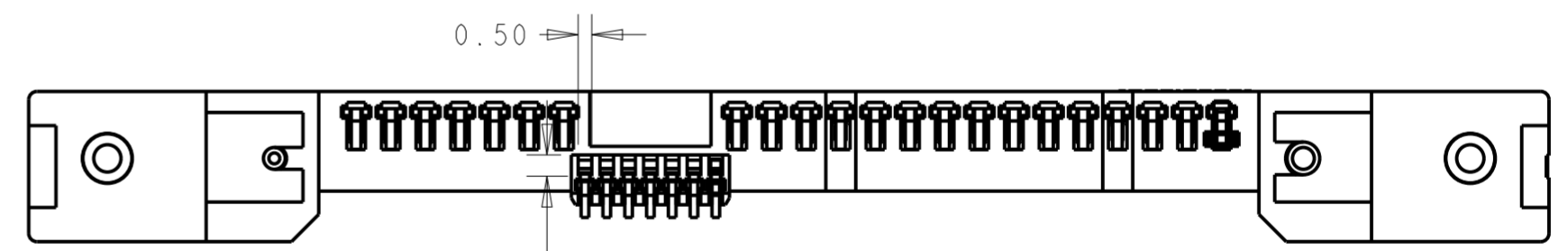
THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN TY PANG 15MAR2011	Tyco Electronics Singapore Pte. Ltd.	
DIMENSIONS: mm		CHK SF LEONG 15MAR2011		
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.20 3 PLC ± 4 PLC ± ANGLES ±3° FINISH		APVD SF LEONG 15MAR2011	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, SMT, SOLDERABLE POST	
MATERIAL		PRODUCT SPEC 108-51067	SIZE A2	
		APPLICATION SPEC -	CAGE CODE 00779	
		WEIGHT -	DRAWING NO 1735871	
CUSTOMER DRAWING		SCALE 4:1		SHEET 1 OF 3

THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION .19  
 (C) COPYRIGHT 19 BY AMP INCORPORATED. ALL RIGHTS RESERVED.

REVISIONS				DATE	DWN	APVD
LOC	DIST	P	LTR	DESCRIPTION		
DY	-					



1735871-1 & -3 AS SHOWN



0.78 ± 0.04

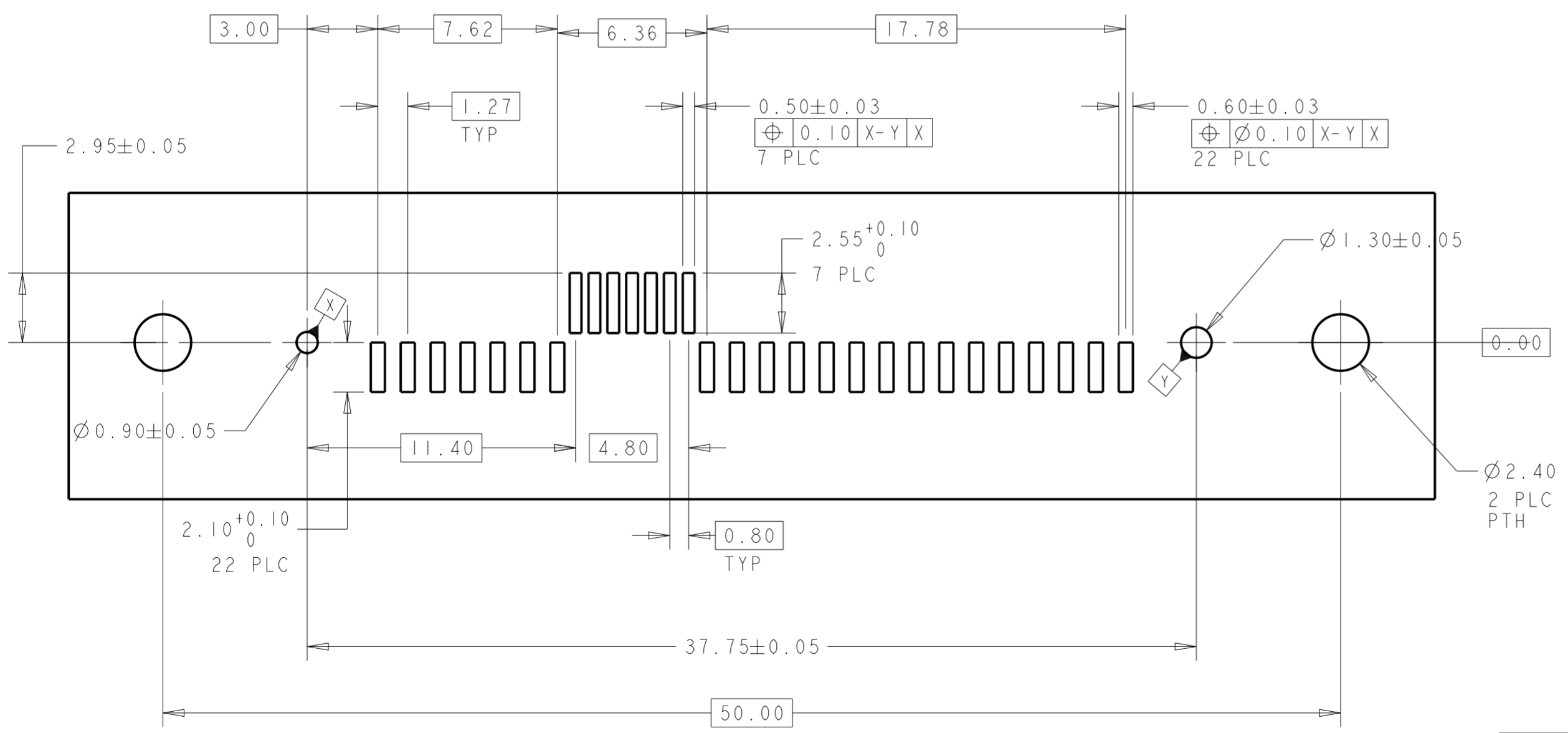
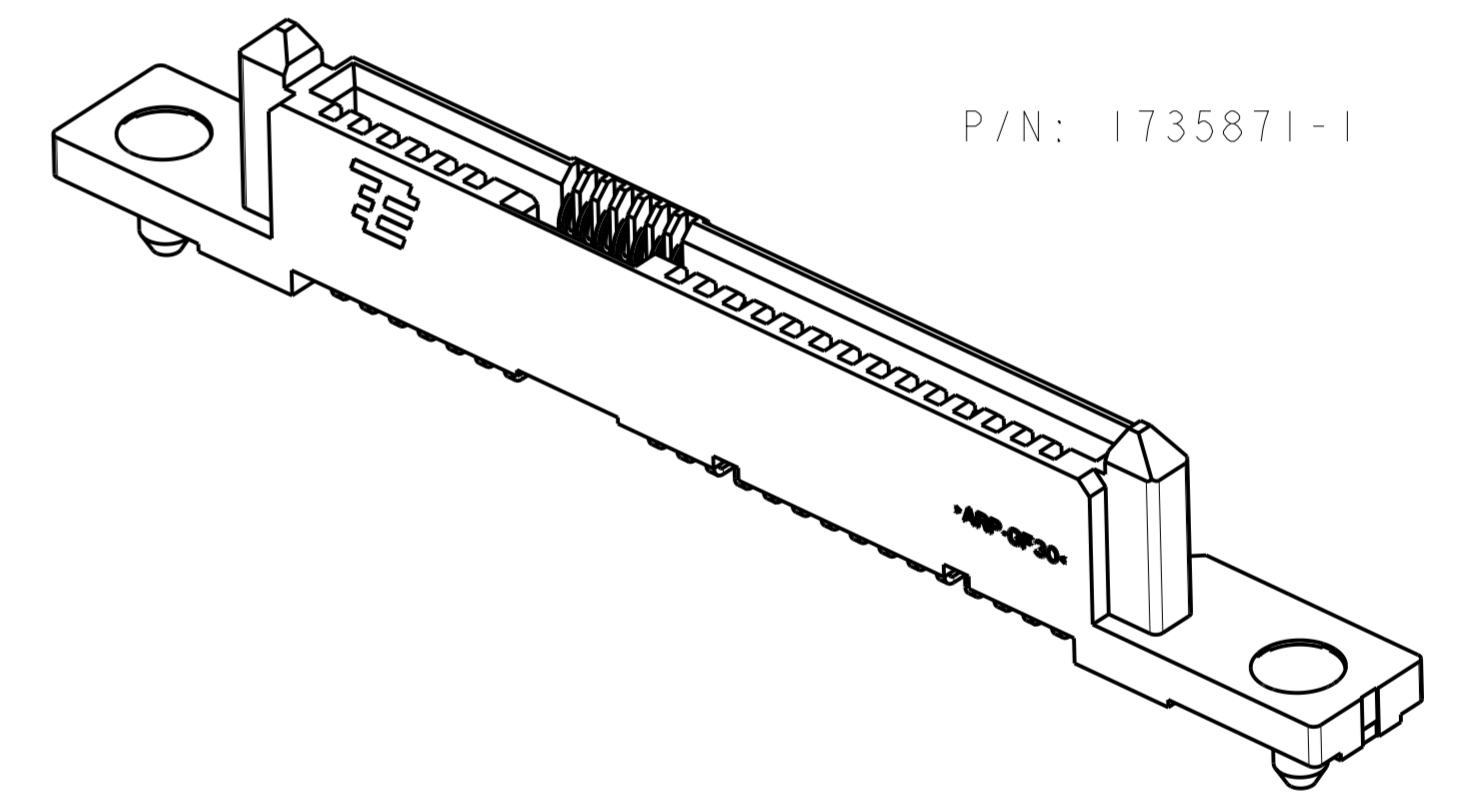
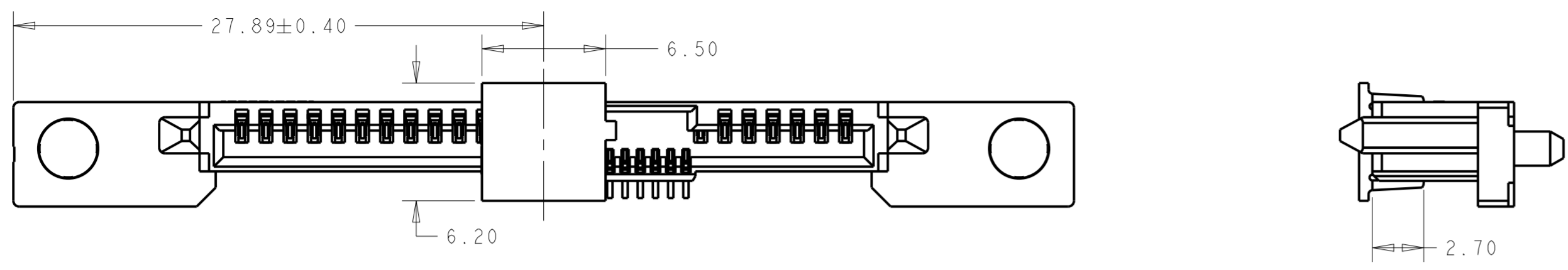
1735871-2 AS SHOWN

<small>THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.</small>		DWN TY PANG 15MAR2011 CHK SF LEONG 15MAR2011 APVD SF LEONG 15MAR2011	Tyco Electronics Singapore Pte. Ltd.		
DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.20 3 PLC ± 4 PLC ± ANGLES ±3° FINISH	PRODUCT SPEC 108-51067 APPLICATION SPEC - WEIGHT -	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, SMT, SOLDERABLE POST		
MATERIAL		CUSTOMER DRAWING	SIZE A2 CAGE CODE 00779	DRAWING NO. 1735871	SCALE 4:1 SHEET 2 OF 3 REV B

THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION .19  
COPYRIGHT 19 BY AMP INCORPORATED. ALL RIGHTS RESERVED.

LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
DY	-	SEE SHEET 1	-	-	-

P/N: 1735871-1 WITH CAP AS SHOWN



RECOMMENDED PCB LAYOUT  
SCALE 5:1

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN TY PANG 15MAR2011	<b>tyco</b> Electronics		Tyco Electronics Singapore Pte. Ltd.
DIMENSIONS: mm		CHK SE LEONG 15MAR2011	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, SMT, SOLDERABLE POST		
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ±0.20 3 PLC ± - 4 PLC ± - ANGLES ±3° FINISH		APVD SE LEONG 15MAR2011	PRODUCT SPEC 108-51067		
MATERIAL		APPLICATION SPEC -	WEIGHT -	SIZE A2	CAGE CODE 00779
		CUSTOMER DRAWING		DRAWING NO 1735871	SCALE 4:1 SHEET 3 OF 3 REV B